PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Wei-Chieh Lin	09/14/2009
Ho-Tai Chen	09/14/2009
Jen-Hao Yeh	09/14/2009
Li-Cheng Lin	09/14/2009
Shih-Chieh Hung	09/14/2009

RECEIVING PARTY DATA

Name:	Anpec Electronics Corporation
Street Address:	No. 6, Dusing 1St Rd., Hsinchu Science Park
City:	Hsin-Chu
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12563172

CH $40.00 12563172

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	ANPP0047USA
NAME OF SUBMITTER:	WINSTON HSU

Total Attachments: 4
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Docket No ANPP0047USA

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar ($1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Wei-Chieh Lin Nationality: TWN

Name: Ho-Tai Chen Nationality: TWN

Name: Jen-Hao Yeh Nationality: TWN

Name: Li-Cheng Lin Nationality: TWN

Name: Shih-Chieh Hung Nationality: TWN

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: Anpec Electronics Corporation

Address: No. 6, Dusing 1St Rd., Hsinchu Science Park, Hsin-Chu 300, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

> "INTEGRATED STRUCTURE OF IGBT AND DIODE AND METHOD OF FORMING THE SAME"

Which is found in :

(a) ___+___ U.S. patent application executed on even date

(b) _________ U.S. patent application executed on _______________________

(c) _________ U.S. application serial no.______________________________

(d) _______ patent no. ____________________ issued ______________________ and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof

IN WITNESS WHEREOF, We have hereunto set hand and seal this 9.14.2009 (Date of signing).（請發明人務必簽署上列日期）

(Type name of inventor)	**Signature of INVENTOR**
Wei-Chieh Lin	WEI-CHIEH LIN
Ho-Tai Chen	Ho-Tai Chen
Jen-Hao Yeh	Jen-Hao Yeh
Li-Cheng Lin	Li-Cheng Lin
Shih-Chieh Hung	Shih-Chieh Hung